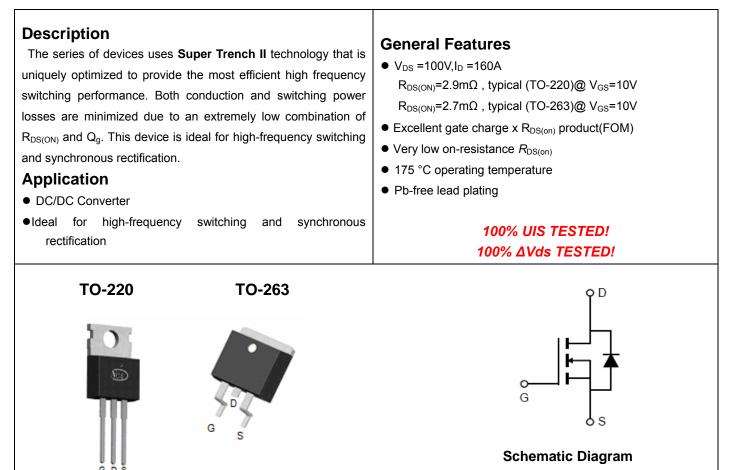


# NCE N-Channel Super Trench II Power MOSFET



## Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP033N10M	NCEP033N10M	TO-220	-	-	-
NCEP033N10MD	NCEP033N10MD	TO-263	-	-	-

### Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	100	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	Ι <sub>D</sub>	160	А
Drain Current-Continuous(Tc=100℃)	I <sub>D</sub> (100℃)	120	А
Pulsed Drain Current (Note 1)	I <sub>DM</sub>	640	А
Maximum Power Dissipation	PD	245	W
Derating factor		1.63	W/℃
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	1345	mJ
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 175	°C



## **Thermal Characteristic**

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	R <sub>θJC</sub>	0.61	°C <b>/W</b>
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\thetaJA}$	60	°C <b>/W</b>

### Electrical Characteristics (T<sub>C</sub>=25<sup>°</sup>C unless otherwise noted)

Parameter	Symbol	Condition		Min	Тур	Max	Unit
Off Characteristics							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250µA		100		-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V,V <sub>GS</sub> =0V		-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	$V_{GS}$ =±20V, $V_{DS}$ =0V		-	-	±100	nA
On Characteristics (Note 3)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =2	50µA	2.0	3.0	4.0	V
	D		TO-220	-	2.9	3.3	mΩ
Drain-Source On-State Resistance	n-Source On-State Resistance R <sub>DS(ON)</sub> V <sub>GS</sub> =10V, I <sub>D</sub> =80A TO-263	TO-263		2.7	3.3	mΩ	
Gate resistance	R <sub>G</sub>			-	2.0	-	Ω
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =5V,I <sub>D</sub> =80A		85	-	-	S
Dynamic Characteristics (Note4)							
Input Capacitance	Clss	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V, F=1.0MHz		-	7810.5	-	PF
Output Capacitance	Coss			-	887.3	-	PF
Reverse Transfer Capacitance	Crss			-	30	-	PF
Switching Characteristics (Note 4)							
Turn-on Delay Time	t <sub>d(on)</sub>			-	25	-	nS
Turn-on Rise Time	tr	V <sub>DD</sub> =50V,I <sub>D</sub> =80A V <sub>GS</sub> =10V,R <sub>G</sub> =1.6Ω		-	15	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>			-	52	-	nS
Turn-Off Fall Time	t <sub>f</sub>			-	17	-	nS
Total Gate Charge	Qg	- V <sub>DS</sub> =50V,I <sub>D</sub> =80A, - V <sub>GS</sub> =10V		-	127.7	-	nC
Gate-Source Charge	Q <sub>gs</sub>			-	41.8		nC
Gate-Drain Charge	Q <sub>gd</sub>			-	35.5		nC
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =80A		-		1.2	V
Diode Forward Current (Note 2)	Is			-	-	160	А
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = 80A		-	74	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs <sup>(Note3)</sup>		-	164	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. The value of  $R_{BJA}$  is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^{\circ}$  C. The Power dissipation  $P_{DSM}$  is based on R  $_{BJA}$  and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175° C may be used if the PCB allows it.

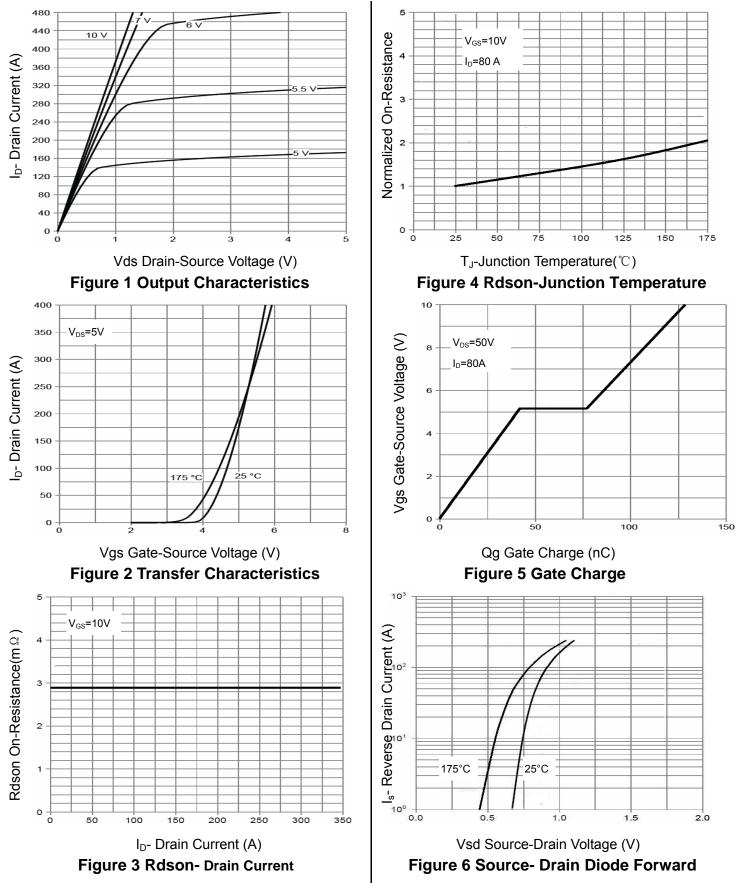
3. Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.

4. Guaranteed by design, not subject to production

5. EAS condition : Tj=25  $^\circ\!\mathrm{C}$  ,V\_DD=50V,V\_G=10V,L=0.5mH,Rg=25 $\Omega$ 



# **Typical Electrical and Thermal Characteristics**





# NCEP033N10M, NCEP033N10MD

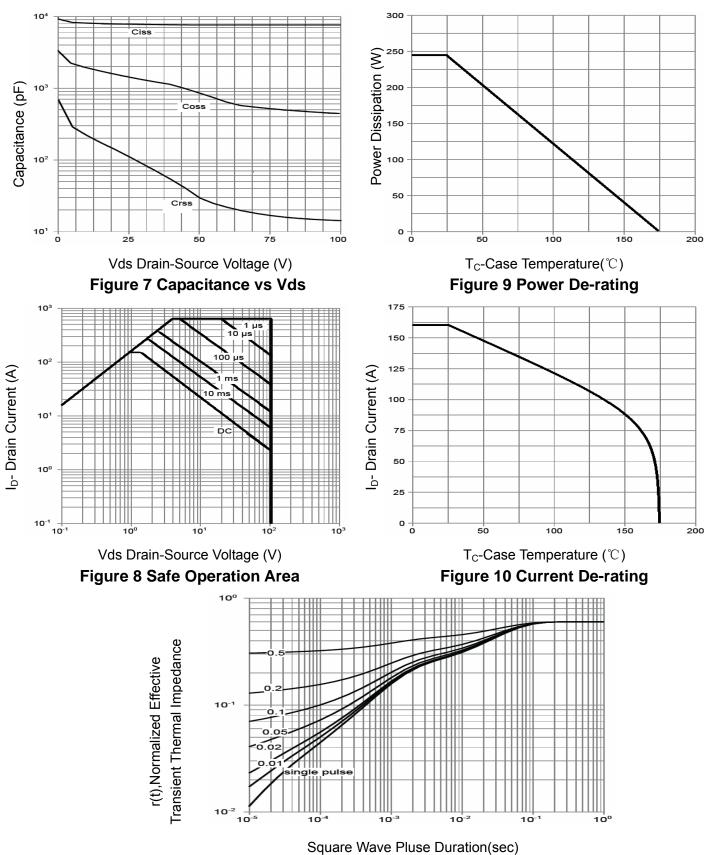
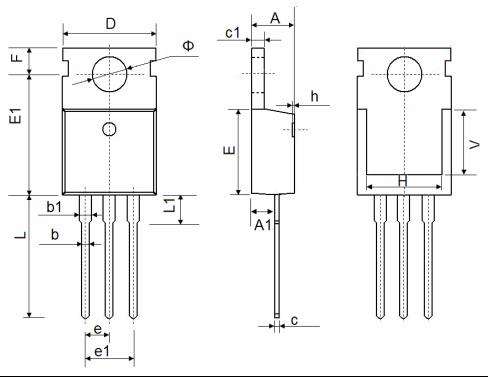


Figure 11 Normalized Maximum Transient Thermal Impedance



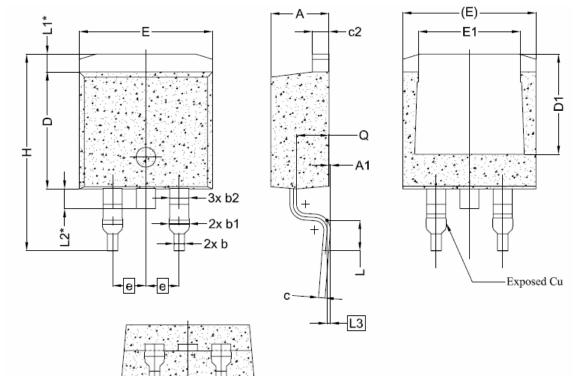
# TO-220-3L Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.400	4.600	0.173	0.181	
A1	2.250	2.550	0.089	0.100	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.330	0.650	0.013	0.026	
c1	1.200	1.400	0.047	0.055	
D	9.910	10.250	0.390	0.404	
E	8.9500	9.750	0.352	0.384	
E1	12.650	12.950	0.498	0.510	
е	2.540	) TYP.	0.100 TYP.		
e1	4.980	5.180	0.196	0.204	
F	2.650	2.950	0.104	0.116	
Н	7.900	8.100	0.311	0.319	
h	0.000	0.300	0.000	0.012	
L	12.900	13.400	0.508	0.528	
L1	2.850	3.250	0.112	0.128	
V	6.900 REF.		0.276 REF.		
Φ	3.400	3.800	0.134	0.150	



# **TO-263-2L Package Information**



Symbol	Dimensions In Millimeters				
Symbol	Min.	Nom.	Max.		
A	4.24	4.44	4.64		
A1	0.00	0.10	0.25		
b	0.70	0.80	0.90		
b1	1.20	1.55	1.75		
b2	1.20	1.45	1.70		
С	0.40	0.50	0.60		
c2	1.15	1.27	1.40		
D	8.82	8.92	9.02		
D1	6.86	7.65	-		
E	9.96	10.16	10.36		
E1	6.89	7.77	7.89		
е	2.54BSC				
Н	14.61 15.00		15.88		
L	1.78 2.32		2.79		
L1	1.36 REF.				
L2	1.50 REF.				
L3	0.25 BSC				
Q	2.30	2.48	2.70		



#### Attention:

- Any and all NCE power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your NCE power representative nearest you before using any NCE power products described or contained herein in such applications.
- NCE power assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all NCE power products described or contained herein.
- Specifications of any and all NCE power products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- NCE power Semiconductor CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all NCE power products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of NCE power Semiconductor CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. NCE power believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the NCE power product that you intend to use.
- This catalog provides information as of Sep.2010. Specifications and information herein are subject to change without notice.